

# NP16N04YUG

#### MOS FIELD EFFECT TRANSISTOR

R07DS0362EJ0100 Rev.1.00 Jun 13, 2011

#### **Description**

The NP16N04YUG is N-channel MOS Field Effect Transistor designed for high current switching applications.

#### **Features**

- Low on-state resistance
  - ---  $R_{DS(on)}$  = 25 mΩ MAX. ( $V_{GS}$  = 10 V,  $I_D$  = 8 A)
- Low  $C_{iss}$ :  $C_{iss} = 740 \text{ pF TYP.}$   $(V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V})$
- Designed for automotive application and AEC-Q101 qualified
- Small size package 8-pin HSON

#### **Ordering Information**

| Part No.            | Lead Plating  | Pac              | Package          |            |
|---------------------|---------------|------------------|------------------|------------|
| NP16N04YUG-E1-AY *1 | Pure Sn (Tin) | Tape 2500 p/reel | Taping (E1 type) | 8-pin HSON |
| NP16N04YUG-E2-AY *1 |               |                  | Taping (E2 type) |            |

Note: \*1. Pb-free (This product does not contain Pb in the external electrode.)

#### Absolute Maximum Ratings ( $T_A = 25^{\circ}C$ )

| Item   | Symbol                | Ratings     | Unit |
|--|-----------------------|-------------|------|
| Drain to Source Voltage (V <sub>GS</sub> = 0 V)    | $V_{DSS}$             | 40          | V    |
| Gate to Source Voltage (V <sub>DS</sub> = 0 V)     | $V_{GSS}$             | ±20         | V    |
| Drain Current (DC) (T <sub>C</sub> = 25°C)         | I <sub>D(DC)</sub>    | ±16         | Α    |
| Drain Current (pulse) *1                           | I <sub>D(pulse)</sub> | ±48         | Α    |
| Total Power Dissipation (T <sub>C</sub> = 25°C)    | P <sub>T1</sub>       | 36          | W    |
| Total Power Dissipation (T <sub>A</sub> = 25°C) *2 | P <sub>T2</sub>       | 1.0         | W    |
| Channel Temperature                                | T <sub>ch</sub>       | 175         | °C   |
| Storage Temperature                                | T <sub>stg</sub>      | −55 to +175 | °C   |
| Repetitive Avalanche Current *3                    | I <sub>AR</sub>       | 13          | Α    |
| Repetitive Avalanche Energy *3                     | E <sub>AR</sub>       | 12          | mJ   |

#### **Thermal Resistance**

Channel to Case Thermal Resistance  $R_{th(ch-C)}$  4.17 °C/W Channel to Ambient Thermal Resistance \*2  $R_{th(ch-A)}$  150 °C/W

Notes: \*1.  $T_C$  = 25°C, PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

\*2. Mounted on glass epoxy substrate of 40 mm x 40 mm x 1.6 mmt with 4% copper area (35  $\mu$ m)

\*3.  $T_{ch(peak)} \le 150^{\circ}C$ ,  $R_G = 25 \Omega$ 

Caution This product is an electrostatic-sensitive device due to low ESD capability and should be handled with caution for electrostatic discharge. HBM (C = 100 pF, R = 1.5 k $\Omega$ )  $\pm$  500 V.

### Electrical Characteristics ( $T_A = 25^{\circ}C$ )

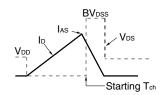
| Item                                      | Symbol              | MIN. | TYP. | MAX. | Unit | Test Conditions                                   |
|---|---------------------|------|------|------|------|---|
| Zero Gate Voltage Drain Current           | I <sub>DSS</sub>    |      |      | 1    | μΑ   | $V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$     |
| Gate Leakage Current                      | I <sub>GSS</sub>    |      |      | ±100 | nA   | $V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$ |
| Gate to Source Threshold Voltage          | $V_{GS(th)}$        | 2.0  | 3.0  | 4.0  | V    | $V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$        |
| Forward Transfer Admittance *1            | y <sub>fs</sub>     | 4    | 8    |      | S    | $V_{DS} = 5 \text{ V}, I_{D} = 8 \text{ A}$       |
| Drain to Source On-state<br>Resistance *1 | R <sub>DS(on)</sub> |      | 20   | 25   | mΩ   | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 8 A      |
| Input Capacitance                         | C <sub>iss</sub>    |      | 740  | 1110 | pF   | $V_{DS} = 25 V$ ,                                 |
| Output Capacitance                        | Coss                |      | 83   | 110  | pF   | $V_{GS} = 0 V$ ,                                  |
| Reverse Transfer Capacitance              | C <sub>rss</sub>    |      | 57   | 100  | pF   | f = 1 MHz   |
| Turn-on Delay Time                        | t <sub>d(on)</sub>  |      | 10   | 20   | ns   | $V_{DD} = 20 \text{ V}, I_D = 8 \text{ A},$       |
| Rise Time                                 | t <sub>r</sub>      |      | 4    | 10   | ns   | $V_{GS}$ = 10 $V$ ,                               |
| Turn-off Delay Time                       | $t_{d(off)}$        |      | 19   | 38   | ns   | $R_G = 0 \Omega$                                  |
| Fall Time                                 | t <sub>f</sub>      |      | 5    | 13   | ns   |   |
| Total Gate Charge                         | $Q_{G}$             |      | 16   | 24   | nC   | V <sub>DD</sub> = 32 V,                           |
| Gate to Source Charge                     | $Q_{GS}$            |      | 5    |      | nC   | $V_{GS} = 10 \text{ V},$                          |
| Gate to Drain Charge                      | $Q_{GD}$            |      | 6    |      | nC   | I <sub>D</sub> = 16 A                             |
| Body Diode Forward Voltage *1             | $V_{F(S-D)}$        |      | 0.9  | 1.5  | V    | I <sub>F</sub> = 16 A, V <sub>GS</sub> = 0 V      |
| Reverse Recovery Time                     | t <sub>rr</sub>     |      | 25   |      | ns   | I <sub>F</sub> = 16 A, V <sub>GS</sub> = 0 V,     |
| Reverse Recovery Charge                   | Q <sub>rr</sub>     |      | 24   |      | nC   | di/dt = 100 A/μs                                  |

Note: \*1. Pulsed test

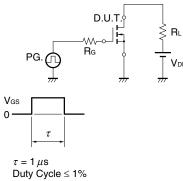
#### **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

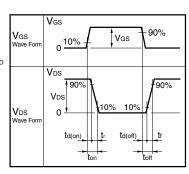
# D.U.T.

$$\begin{array}{c} \text{RG} = 25 \ \Omega \\ \text{PG.} \\ \text{V}_{\text{GS}} = 20 \rightarrow 0 \ \text{V} \end{array} \begin{array}{c} \text{PG.} \\ \text{$>$} 50 \ \Omega \\ \text{$>$} \end{array} \begin{array}{c} \text{$\downarrow$} \\ \text{$\downarrow$} \end{array} \begin{array}{c} \text{$\downarrow$} \\ \text{$\downarrow$} \\ \text{$\downarrow$} \end{array}$$



#### TEST CIRCUIT 2 SWITCHING TIME

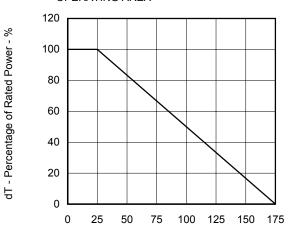




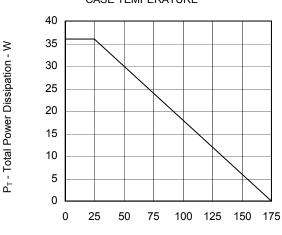
#### **TEST CIRCUIT 3 GATE CHARGE**

#### Typical Characteristics ( $T_A = 25^{\circ}C$ )

DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA

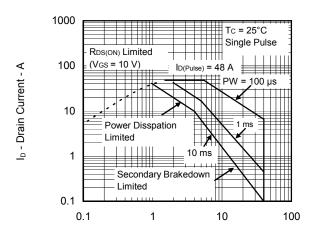


TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



# FORWARD BIAS SAFE OPERATING AREA

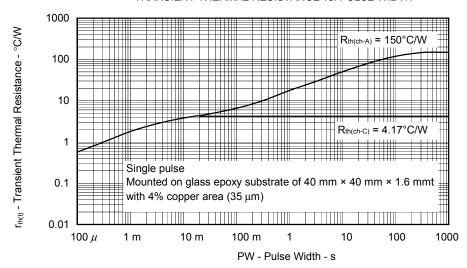
T<sub>C</sub> - Case Temperature - °C



T<sub>C</sub> - Case Temperature - °C

 $V_{\text{\scriptsize DS}}$  - Drain to Source Voltage - V

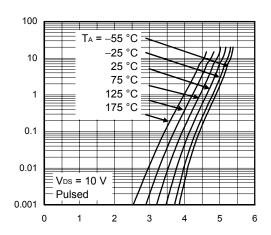
#### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



V<sub>GS(th)</sub> - Gate to Source Threshold Voltage - V

 $R_{\text{DS}(\text{on})}$  - Drain to Source On-state Resistance -  $m\Omega$ 

#### DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE 60 50 Ip - Drain Current - A 40 V<sub>GS</sub> = 10 V 30 20 10 Pulsed 0 0 0.5 1 1.5 2

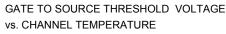


Ip - Drain Current - A

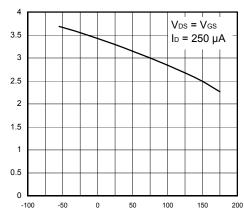
| y<sub>fs</sub> | - Forward Transfer Admittance - S

FORWARD TRANSFER CHARACTERISTICS

V<sub>GS</sub> - Gate to Source Voltage - V

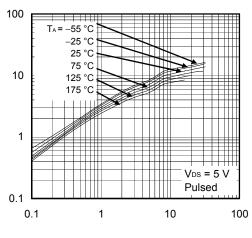


V<sub>DS</sub> - Drain to Source Voltage - V



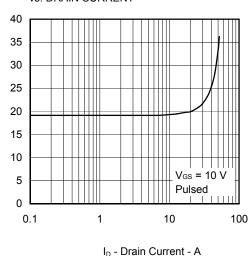
T<sub>ch</sub> - Channel Temperature - °C

# FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

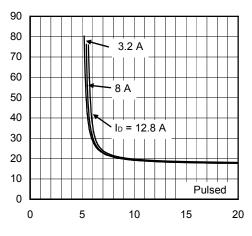


I<sub>D</sub> - Drain Current - A

# DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

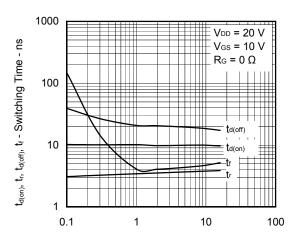


 $V_{\text{GS}}$  - Gate to Source Voltage - V

 $R_{\text{DS(on)}}$  - Drain to Source On-state Resistance -  $m\Omega$ 

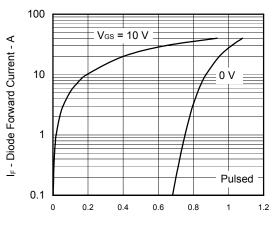
T<sub>ch</sub> - Channel Temperature - °C

#### SWITCHING CHARACTERISTICS



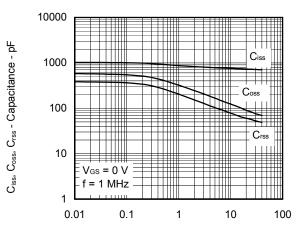
 $I_{\text{D}}$  - Drain Current - A

#### SOURCE TO DRAIN DIODE FORWARD VOLTAGE



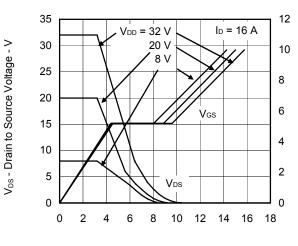
 $V_{\text{F(S-D)}}$  - Source to Drain Voltage - V

#### CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



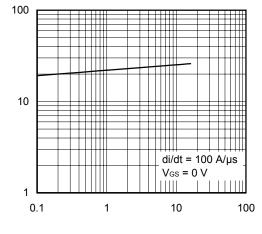
V<sub>DS</sub> - Drain to Source Voltage - V

#### DYNAMIC INPUT/OUTPUT CHARACTERISTICS



Q<sub>G</sub> - Gate Charge - nC

# REVERSE RECOVERY TIME vs. DRAIN CURRENT

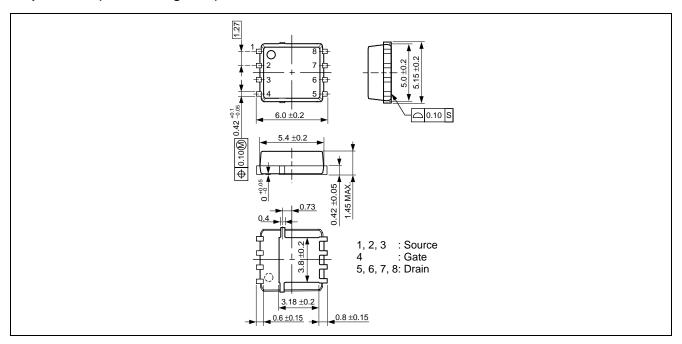


I<sub>F</sub> - Drain Current - A

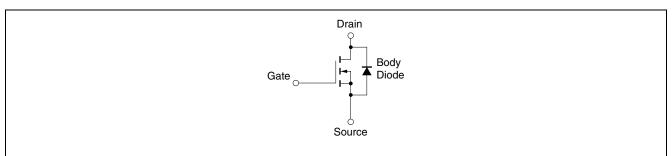
t<sub>rr</sub> - Reverse Recovery Time - ns

#### Package Drawings (Unit: mm)

8-pin HSON (Mass: 0.13 g TYP.)



#### **Equivalent Circuit**



**Remark** Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

**Revision History** 

### NP16N04YUG Data Sheet

|      |              | Description |                      |  |
|------|--------------|-------------|----------------------|--|
| Rev. | Date         | Page        | Summary              |  |
| 1.00 | Jun 13, 2011 | _           | First Edition Issued |  |

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